

SOLDER ALLOY, SOLDER BALL, SOLDER PREFORM, SOLDER PASTE, AND SOLDER JOINT

ABSTRACT

Provided are a solder alloy and a solder joint which have excellent wettability and high reliability by prevention of rupture of solder joints. The solder alloy has an alloy composition consisting of, by mass%, Ag: 1.0 to 3.7%, Cu: 0.4 to 0.8%, Sb: 0.50 to 2.90%, In: 5.00 to 10.00%, and Ni: 0.01 to 0.06%, with the balance being Sn.

[Figure 1A]